Guidelines for IC FabLab Report

• Cover with group names and responsibility
• Acknowledgement
• Abstract
• Chapter 1: Technical Background
  – Introduction
  – Device Physics
  – Process Considerations
  – Basic NMOS Processing
  – Processing & Device Modeling –T-SUPREM & MEDICI
  – Device Characteristics & Testing Techniques
• Chapter 2: Processing Procedures
  – Detailed process flows with comments
  – Inspection results with photos
• Chapter 3: Electrical Test Results and Discussions
  – I-V, C-V, Device variations, etc., with tables/plots
• Chapter 4: Summary & Conclusions
• References & Appendix